

GRINDING METHOD FOR CIRCULAR PLATE-SHAPED WORKPIECE

ABSTRACT

There is provided a grinding method that is applied when a workpiece having a first surface and a second surface is to be ground from the second surface. The grinding method includes a first grinding step of causing first grindstones to come into contact with the workpiece to grind the workpiece and thereby form on the workpiece a circular plate-shaped first thin plate portion and an annular first thick plate portion surrounding the first thin plate portion, and a second grinding step of causing second grindstones to come into contact with the first thick plate portion and the first thin plate portion to grind the workpiece and thereby form on the workpiece a thin circular plate-shaped second thin plate portion that has a larger diameter than the first thin plate portion and an annular second thick plate portion surrounding the second thin plate portion.

[FIG. 6]